FAIRCHILD SEMICONDUCTOR®

April 2002

FDC6392S

20V Integrated P-Channel PowerTrench® MOSFET and Schottky Diode

General Description

The FDC6392S combines the exceptional performance of Fairchild's PowerTrench MOSFET technology with a very low forward voltage drop Schottky barrier rectifier in an SSOT-6 package.

This device is designed specifically as a single package solution for DC to DC converters. It features a fast switching, low gate charge MOSFET with very low on-state resistance. The independently connected Schottky diode allows its use in a variety of DC/DC converter topologies.

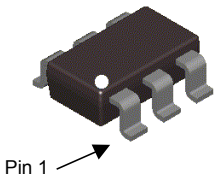
Features

MOSFET:

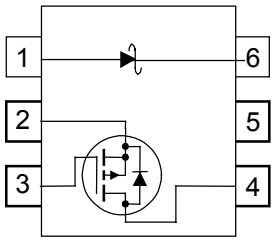
- –2.2 A, –20V. $R_{DS(ON)}$ = 150 mΩ @ V_{GS} = –4.5V
  $R_{DS(ON)}$ = 200 mΩ @ V_{GS} = –2.5V
- Low Gate Charge (3.7nC typ)
- Compact industry standard SuperSOT™-6 package

Schottky:

- V_F < 0.45 V @ 1 A



SuperSOT™-6



Absolute Maximum Ratings

T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	MOSFET Drain-Source Voltage		–20	V
V_{GSS}	MOSFET Gate-Source Voltage		±12	V
I_D	Drain Current – Continuous	(Note 1a)	–2.2	A
	– Pulsed		–6	
P_D	Power Dissipation for Single Operation	(Note 1a)	0.96	W
		(Note 1b)	0.9	
		(Note 1c)	0.7	
T_J, T_{STG}	Operating and Storage Junction Temperature Range		–55 to +150	°C
V_{RRM}	Schottky Repetitive Peak Reverse Voltage		20	V
I_O	Schottky Average Forward Current	(Note 1a)	1	A

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	130	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	60	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
.392	FDC6392S	7''	8mm	3000 units

Electrical Characteristics

T_A = 25°C unless otherwise noted

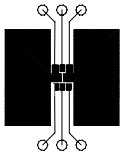
Symbol	Parameter	Test Conditions		Min	Typ	Max	Units
Off Characteristics							
BV_{DSS}	Drain–Source Breakdown Voltage	V_{GS} = 0 V, I_D = –250 µA		–20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = –250 µA, Referenced to 25°C			–16		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = –16 V, V_{GS} = 0 V				–1	µA
I_{GSSF}	Gate–Body Leakage, Forward	V_{GS} = 12 V, V_{DS} = 0 V				100	nA
I_{GSSR}	Gate–Body Leakage, Reverse	V_{GS} = –12 V, V_{DS} = 0 V				–100	nA
On Characteristics (Note 2)							
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = –250 µA		–0.6	–1.0	–1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = –250 µA, Referenced to 25°C			3		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	V_{GS} = –4.5 V, I_D = –2.2 A V_{GS} = –2.5 V, I_D = –1.8 A V_{GS}=–4.5 V, I_D =–2.2 A, T_J=125°C			101 152 132	150 200 211	mΩ
$I_{D(on)}$	On–State Drain Current	V_{GS} = –4.5 V, V_{DS} = –5 V		–6			A
g_{FS}	Forward Transconductance	V_{DS} = –5 V, I_D = –2.2 A			6		S
Dynamic Characteristics							
C_{iss}	Input Capacitance	V_{DS} = –10 V, V_{GS} = 0 V, f = 1.0 MHz			369		pF
C_{oss}	Output Capacitance				80		pF
C_{rss}	Reverse Transfer Capacitance				39		pF
R_G	Gate Resistance	V_{GS} = –15 mV, f = 1.0 MHz			7.6		Ω
Switching Characteristics (Note 2)							
$t_{d(on)}$	Turn–On Delay Time	V_{DD} = –10 V, I_D = –1 A, V_{GS} = –4.5 V, R_{GEN} = 6 Ω			8	16	ns
t_r	Turn–On Rise Time				11	20	ns
$t_{d(off)}$	Turn–Off Delay Time				13	23	ns
t_f	Turn–Off Fall Time				4	8	ns
Q_g	Total Gate Charge	V_{DS} = –10 V, I_D = –2.2 A, V_{GS} = –4.5 V			3.7	5.2	nC
Q_{gs}	Gate–Source Charge				1		nC
Q_{gd}	Gate–Drain Charge				1		nC
Drain–Source Diode Characteristics and Maximum Ratings							
I_S	Maximum Continuous Drain–Source Diode Forward Current					–0.8	A
V_{SD}	Drain–Source Diode Forward Voltage	V_{GS} = 0 V, I_S = –0.8 A (Note 2)			–0.8	–1.2	V
t_{rr}	Diode Reverse Recovery Time	I_F = –2.2 A, d_{iF}/d_t = 100 A/µs			5.4		nS
Q_{rr}	Diode Reverse Recovery Charge				1.2		nC
Schottky Diode Characteristics							
I_R	Reverse Leakage	V_R = 20 V	T_J = 25°C		148	400	µA
			T_J = 100°C		14	20	mA
		V_R = 10V	T_J = 25°C		55	200	µA
			T_J = 100°C		5.2	10	mA
V_F	Forward Voltage	I_F = 500mA	T_J = 25°C		0.34	0.4	V
			T_J = 100°C		0.26	0.35	
		I_F = 1 A	T_J = 25°C		0.40	0.45	V
			T_J = 100°C		0.35	0.42	

Electrical Characteristics

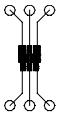
T_A = 25°C unless otherwise noted

Notes:

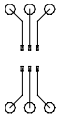
1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 130 °C/W when mounted on a 0.125 in^2 pad of 2 oz. copper.



b) 140°C/W when mounted on a .004 in^2 pad of 2 oz copper



c) 180°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

Typical Characteristics

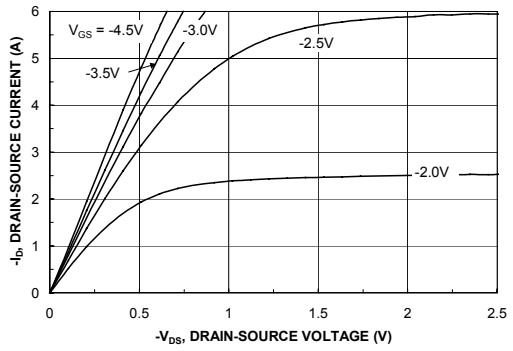


Figure 1. On-Region Characteristics.

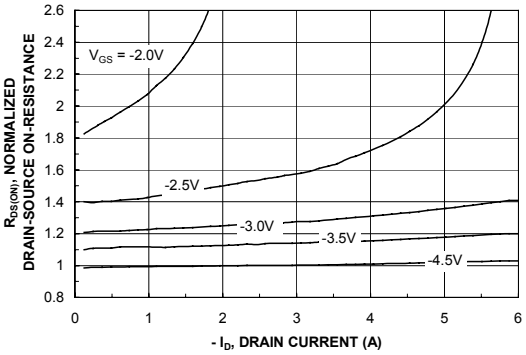


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

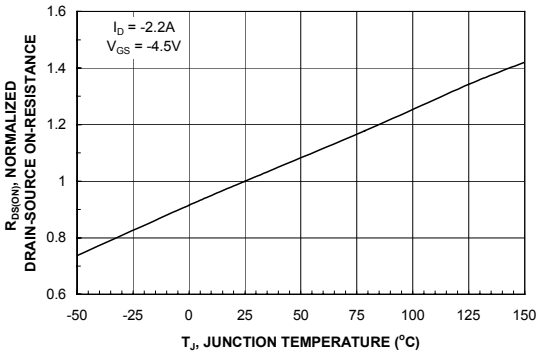


Figure 3. On-Resistance Variation with Temperature.

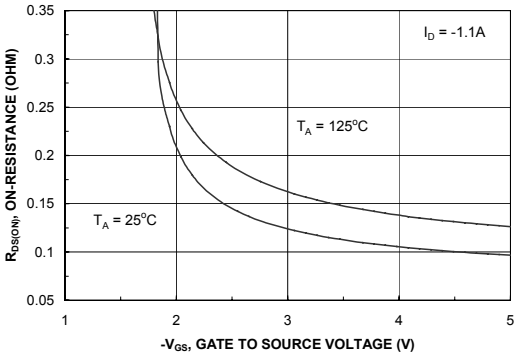


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

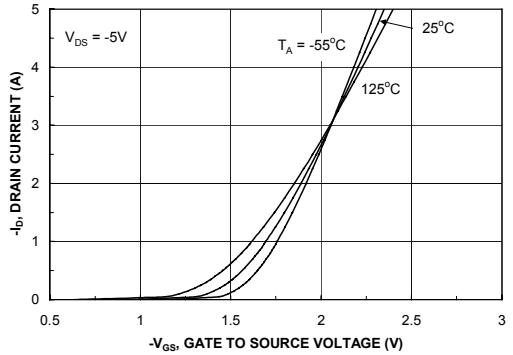


Figure 5. Transfer Characteristics.

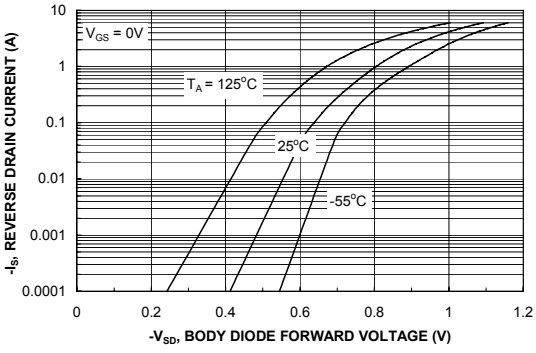


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

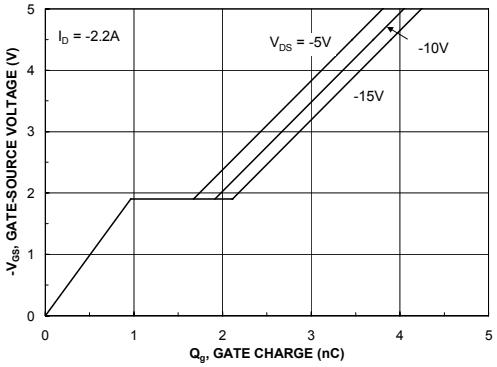


Figure 7. Gate Charge Characteristics.

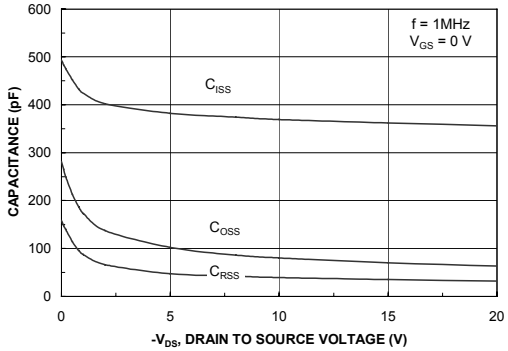


Figure 8. Capacitance Characteristics.

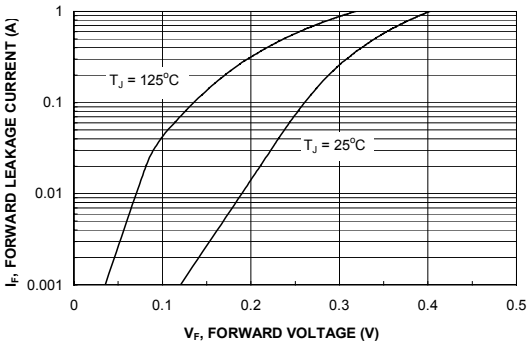


Figure 9. Schottky Diode Forward Voltage.

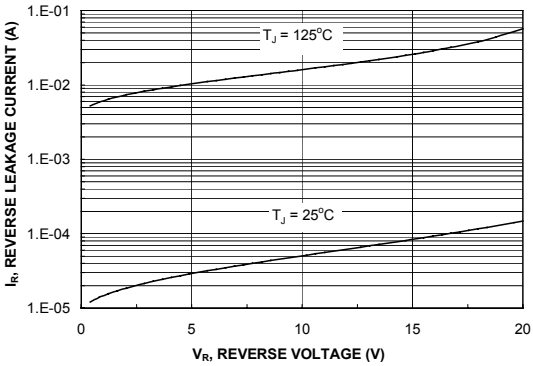


Figure 10. Schottky Diode Reverse Current.

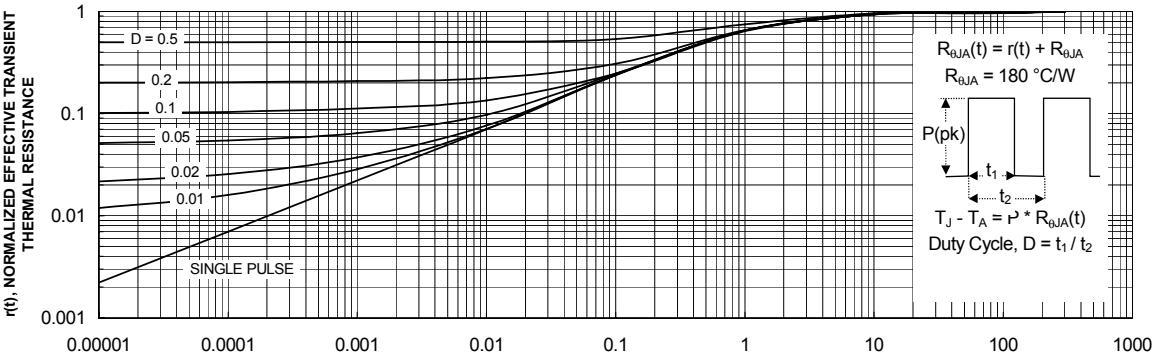


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.
Transient thermal response will change depending on the circuit board design.

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	FAST ®	MICROWIRE™	SILENT SWITCHER ®	UHC™
Bottomless™	FASTr™	OPTOLOGIC ®	SMART START™	UltraFET ®
CoolFET™	FRFET™	OPTOPLANAR™	SPM™	VCX™
CROSSVOLT™	GlobalOptoisolator™	PACMAN™	STAR*POWER™	
DenseTrench™	GTO™	POP™	Stealth™	
DOME™	HiSeC™	Power247™	SuperSOT™-3	
EcoSPARK™	I^2C™	PowerTrench ®	SuperSOT™-6	
E^2CMOS^{TM}	ISOPLANAR™	QFET™	SuperSOT™-8	
$EnSigna^{TM}$	LittleFET™	QS™	SyncFET™	
FACT™	MicroFET™	QT Optoelectronics™	TinyLogic™	
FACT Quiet Series™	MicroPak™	Quiet Series™	TruTranslation™	

STAR*POWER is used under license

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.
As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.